

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,917,107 B2
APPLICATION NO. : 10/772204
DATED : July 12, 2005
INVENTOR(S) : Salman Akram

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 4, line 30 –

Replace “conductive material **80** can it improve dissipation of heat”
With --conductive material **80** can improve dissipation of heat--

Col. 4, line 44 –

Replace “**80** contacts substrate **52** at a first location **82** proximate first”
With --**80** contacts substrate **52** at a first location **82** proximate first--

Col. 5, line 10 –

Replace “second surface **66** to **5** die **62**, with die **62** being illustrated”
With --second surface **66** of die **62**, with die **62** being illustrated--

Col. 7, line 11 –

Replace “Thermally conductive a material **80 e** can this comprise”
With --Thermally conductive material **80 e** can this comprise--

Col. 7, line 41 –

Replace “plurality of chips **62f** formed if over substrate **52f**. Substrate”
With --plurality of chips **62f** formed over substrate **52f**. Substrate--

Col. 7, line 44 –

Replace “A plurality-of slits **54f** extend through substrate **52f**.”
With --A plurality of slits **54f** extend through substrate **52f**--

Col. 7, line 50 –

Replace “connected is with the circuitry on surface **56f** with electrical”
With --connected with the circuitry on surface **56f** with electrical--

Col. 8, line 34 –

Replace “to locations wherein thermally **13** conductive”
With --to locations wherein thermally conductive--

Col. 9, line 14 –

Replace “is wrapped **12** around chip **62g**. In the shown embodiment”
With --is wrapped around chip **62g**. In the shown embodiment--

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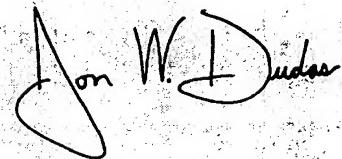
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 9, line 46 -

Replace "of 18 chip 62g."
With --of chip 62g.--

Signed and Sealed this

Fifteenth Day of August, 2006



JON W. DUDAS
Director of the United States Patent and Trademark Office